





• Chip Type, high voltage and long life.

- ●Load life of 10000 hours at +105°C
- Applicable to automatic mounting machine using carrier tape.
- Adapted to the RoHS directive (2011/65/EU).

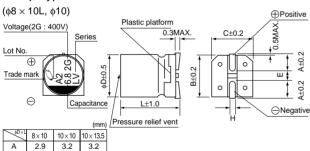




### Specifications

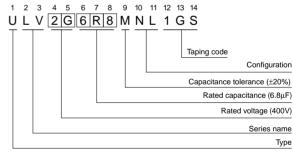
Item	Performance Characteristics											
Category Temperature Range	40 to +105°C											
Rated Voltage Range	60 to 450V											
Rated Capacitance Range	3.3 to 33µF											
Capacitance Tolerance	10% at 120Hz, 20°C											
Leakage Current	After 1 minute's application of rated voltage, leakage current is not more than 0.04CV+100 (µA).											
Tangent of loss angle (tan $\delta)$	Measurement frequency : 120Hz at 20°C        ed voltage (V)      160      200      250      400      450        an δ (MAX.)      0.20      0.25      0.25      0.30											
	Measurement frequency: 120Hz											
Stability at Low Temperature	Rated voltage (V)      160      200      250      400      450											
	Impedance ratio      Z-40°C / Z+20°C      6      6      10      10      15											
Endurance	Capacitance specifications listed at right shall be met when the capacitors are restored to 20°C after the rated voltage is applied for 10000 hours at 105°C.Capacitance changeWithin $\pm 30\%$ of the initial capacitance value tan $\delta$ Solution of the initial capacitance valueLeakage currentLeakage currentLess than or equal to the initial specified value											
Shelf Life	After storing the capacitors under no load at 105°C for 1000 hours and then performing voltage treatment based on JIS C 5101-4 clause 4.1 at 20°C, they shall meet the specified values for the endurance characteristics listed above.											
Resistance to soldering heat	The capacitors are kept on a hot plate for 30 seconds, which is maintained at 250°C and then performing voltage treatment based on JIS C 5101-4 clause 4.1 at 20°C, they shall meet the characteristic requirements listed at right when they are removed from the plate. Capacitance change Within $\pm 10\%$ of the initial capacitance value tan $\delta$ Less than or equal to the initial specified value Leakage current Less than or equal to the initial specified value											
Marking	Black print on the case top.											

### Chip Type



<u>٦</u>	2.9	3.2	3.2						
В	8.3	10.3	10.3						
С	8.3	10.3	10.3	Voltage					
Е	3.1	4.5	4.5	vollage	400	000	050	400	т
L	10	10	13.5	V	160	200	250	400	
Н	0.8 to 1.1	0.8 to 1.1	0.8 to 1.1	Code	2C	2D	2E	2G	

# Type numbering system (Example : 400V 6.8µF)



#### Dimensions

	V	16	50	20	00	25	50	40	0	450	)
Cap.(µF)	Code	20	С	2	D	2	E	20	3	2W	/
3.3	3R3									8×10	25
3.9	3R9							8×10	35		
5.6	5R6									10×10	40
6.8	6R8							10×10	50		
7.5	7R5									10×13.5	45
8.2	8R2					8×10	35				
10	100							10×13.5	55		
12	120			8×10	50						
15	150	8×10	50			10×10	50				
18	180	1		10×10	65	10×13.5	55				
22	220	10×10	65								
27	270			10×13.5	70					Case size ¢D×L (mm)	Rated
33	330	10×13.5	70							$\phi D \times L (mm)$	ripple

Rated ripple current (mArms) at 105°C 120Hz

• Taping specifications are given in page 23.

• Recommended land size, soldering by reflow are given

in page 18, 19. • Please refer to page 3 for the minimum order quantity.

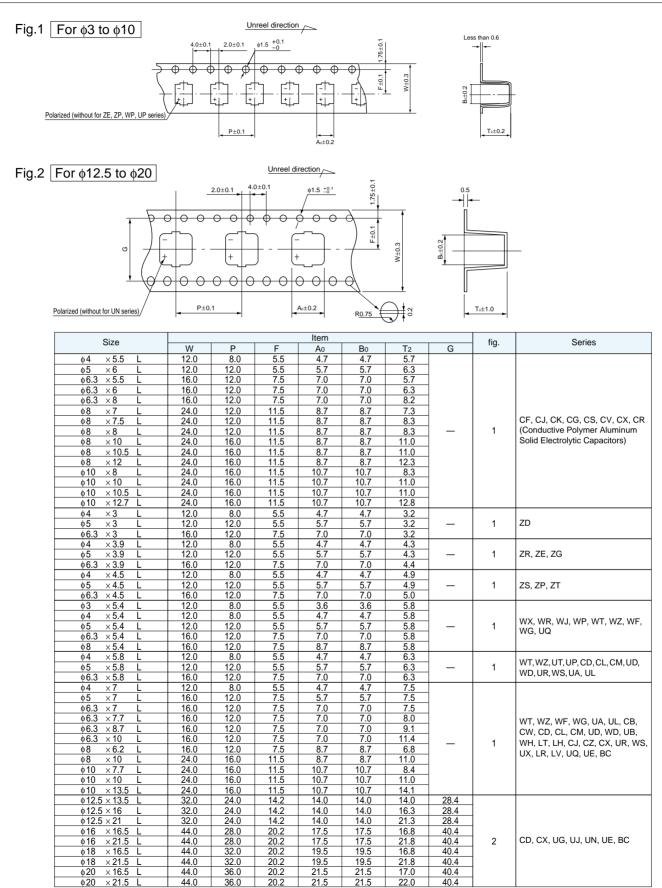
50 Hz 120 Hz 300 Hz Frequency 1 kHz 10 kHz or more Coefficient 0.80 1.60 1.00 1.25 1.40

• Frequency coefficient of rated ripple current

Taping Specifications for Chip Type Capacitors

% Please refer to page28 about the FPCAP product spec.

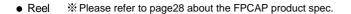
### Carrier tape

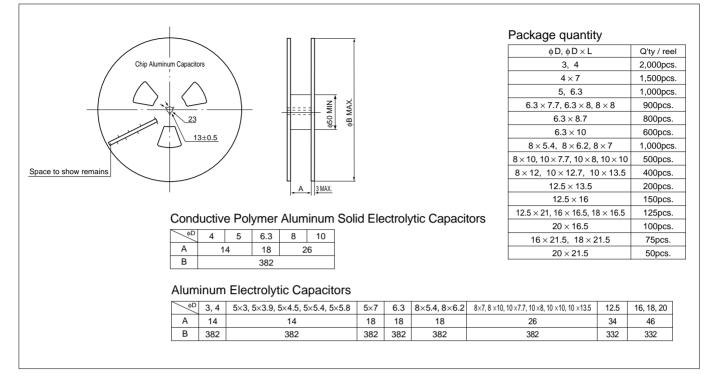


(mm)

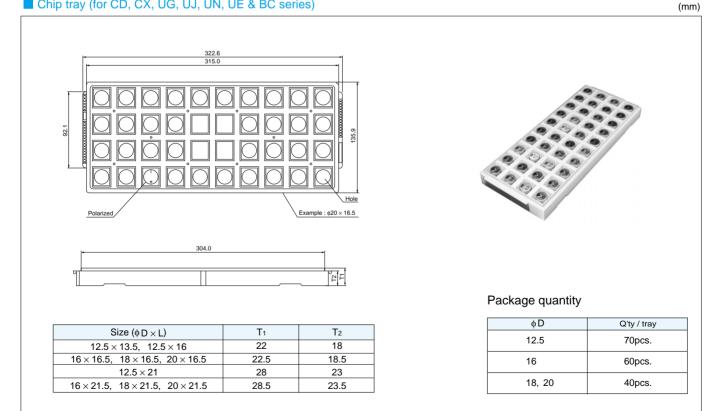
## nichicon

(mm)





#### Chip tray (for CD, CX, UG, UJ, UN, UE & BC series)



CAT.8100C

# **FPCAP** Packaging Unit Quantity for Reel (SMD Type)

PS, PA, HS, HA, SS, SA, SB, FS, FA, SL, VA, VB, VC, UA, UB series

## Components are packaged as per following packing unit.

### Packing Quantity (Reel)

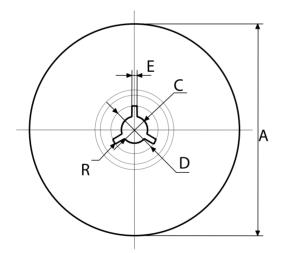
PS, PA, HS, HA, SS, SA, SB, FS, FA, SL series

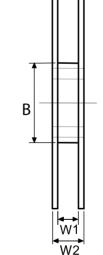
Case Size ¢D×L (mm)	Reel (pcs)
¢4×5.2	2,000
¢5×5.7	1,000
¢6.3×4.2	1,000
¢6.3×5.7	1,000
¢6.3×7.7	900
\$\$ × 6.7	1,000
\$8×7.7	900
\$\$ × 8.7	500
¢8×11.7	500
¢10×7.7	500
¢10×12.4	400

VA, VB, VC, UA	,UB series
Case Size	

L×W×H (mm)	Reel (pcs)
7.3x4.3x1.9	3,000
7.3x4.3x2.8	2,500

Note : Please inquire for FPCAP by Packing Unit as above.





### PS, PA, HS, HA, SS, SA, SB, FS, FA, SL series

Size (dia)	A ± 2.0	В ± 1.0	C ± 0.5	D ±1.0	E ± 0.5	W1 ±1.0	W2 ±1.0	R
4, 5	380	80	13.0	21	2.0	13.4	17.4	1.0
6.3	380	80	13.0	21	2.0	17.4	21.4	1.0
8, 10	380	80	13.0	21	2.0	25.4	29.4	1.0

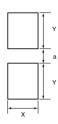
### VA, VB, VC, UA, UB series

Size L×W×H	A ± 2.0	B ± 1.0	C ± 0.5	D ±1.0	E ± 0.5	W1 ± 1.0	W2 ± 1.0	R
7.3×4.3×1.9	330	80	13.0	21	2.0	13.4	17.4	1.0
7.3×4.3×2.8	330	80	13.0	21	2.0	13.4	17.4	1.0

[Unit : mm]

### Surface Mount Type

#### Recommended Land Size (mm)



S		Х	Y		а		
¢	93		1.6	2.2		0.8	
¢	þ4		1.6	2.6			1.0
¢	þ5		1.6	3.0			1.4
φ	6.3		1.6	3.5			1.9
φ8×5.5L	, φ8×6.2	L :	2.5	4.0		2.1	
φ8>	< 10L	:	2.5	3.5		3.0	
φ	10	:	2.5	4.0			4.0
Size	Welde	d termir	nal type	Perpendicul	arly m	ounted t	erminal type
Size	Х	Y	a	Х		Y	а
φ12.5	4.0	7.5	7.0	2.0	7	.3	3.0
φ16	6.0	8.5	9.5	2.0	7	.9	5.3
φ18	6.0	9.5	10.5	2.0	8	.9	5.3
φ20	6.0	9.5	12.5	2.4	8	.7	7.8

\*\* A chip product of \$12.5 or more in size and with a bent terminal shape indicates a product where the 11th digit of the product number code is "Q". Vibration Resistance Type

(CZ, CX, UE, BC series)

① \$6.3 to 10

- /			
Size	Х	Y	а
$\phi 6.3  imes 10L$	3.0	4.0	1.6
$\varphi 8 \times 10 L$	4.3	5.3	2.0
$\phi$ 10 $ imes$ 10L	4.3	5.6	3.3

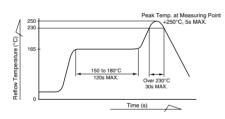
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]c [□	Size	А	В	С	D	Е	F	G
<u>≵₽↓</u>	¢12.5	3.0	2.3	5.0	7.3	7.0	2.0	2.5
А	¢16	5.3	2.9	5.0	7.9	7.0	2.0	2.5
_ <b>↓</b>	φ18	5.3	3.1	5.8	8.9	11.0	2.0	4.5
	¢20	7.8	2.9	5.8	8.7	12.0	2.4	4.8

### Soldering by Reflow

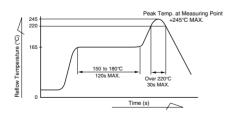
### Table-1

Chip Type Aluminum Electrolytic Capacitors



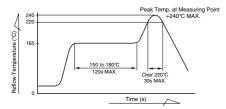
#### Table-2

Chip Type Aluminum Electrolytic Capacitors



#### • Table-3

Chip Type Aluminum Electrolytic Capacitors



#### o 10 or Smaller

(ZS, ZP, ZT, WX<sup>\*1</sup>, WR, WP<sup>\*1</sup>, WT<sup>\*1</sup>, WF, WG, UP, UT, UA, UL, CB, CW, CD<sup>\*2</sup>, CL, CM, UD, UB<sup>\*3</sup>, CJ, CZ, CX<sup>\*2</sup>, UR, UX<sup>\*3</sup>, UQ, UE<sup>\*2</sup>, BC<sup>\*2</sup>)

 $^{*1}\phi 8 \times 5.4L$  : Refer to the table-2  $^{*2}\phi 12.5$  or greater : Refer to the table-4

- \*3160 to 400V : Refer to the table-3
  - 160 to 400V ? Relef to the table-3
    - Pre heating shall be done at +150°C to 180°C and for 120 seconds.
    - The temperature at capacitor Top shall not exceed +250°C.
    - The duration for over +230°C temperature at capacitor surface shall not exceed 30 seconds.
    - The standard temperature profile differs by every reflow method.
    - · Reflow shall be done within 2 cycles. please make sure the parts have enough
    - cooling down time between the first and second soldering process.
    - · Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

#### $\phi 8 \times 5.4L$ (WX, WP, WT)

- Pre heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +245°C.
- The duration for over +220°C temperature at capacitor surface shall not exceed 30 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough
- cooling down time between the first and second soldering process.
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

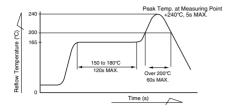
#### 3L, 3.9L (ZD, ZR, ZE, ZG), UX(160 to 400V), UB(160 to 400V) , LT, LH, LR, LV

- Pre heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +240°C.
- The duration for over +220°C temperature at capacitor surface shall not exceed 30 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.( $\phi$  6.3 : 1 cycle only)
- · Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.
- Please contact us if 250°C use of ZG series.



• Table-4

Chip Type Aluminum Electrolytic Capacitors

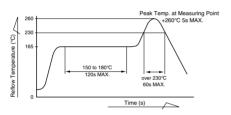


#### \$ 12.5 or greater (CD, CX, UG, UJ, UN, UE, BC)

- Pre heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +240°C.
- The duration for over +200°C temperature at capacitor surface shall not exceed 60 seconds.
- The standard temperature profile differs by every reflow method.
- ${\boldsymbol{\cdot}}$  Reflow shall be done within 2 cycles. please make sure the parts have enough
- cooling down time between the first and second soldering process.
- Please contact us it capacitors are subject to the conditions other than the allowable range at reflow.

#### • Table-5

Chip Type Aluminum Electrolytic Capacitors



#### (For High Temp. Reflow) WJ, WZ, WD, WH, WS

- Pre heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor surface shall not exceed +260°C.
- The duration for over +230°C temperature at capacitor surface shall not exceed 60 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.
  (\u03c6 8 × 6.2 and \u03c6 10 × 10 : 1 cycle only)
- · Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.